

INTRODUCTION

Tantalum capacitor are designed with excellent performance characteristics for filtering, blocking, and R.C tunning circuits. They are used extensively in industrial, commercial, entertainment and medical electronic equipment. They exhibit the proven characteristics of wide temperature range and long-term stability.

The advantages of tantalum capacitor electrolytic capacitor consist of their chemical stability, the low thickness and high dielectric constant of the tantalum oxide layer, and the capability of sintering anodes with a very large surface from tantalum powder.

The low reactivity of the tantalum oxide layer allows the employment of highly conductive electrolytes, and thus achieves a low series resistance. Capacitance and dissipation factor in relation to temperature and frequency thus prove to be very favourable. Additionally, there is also the wide temperature range of several types form -55° C to $+125^{\circ}$ C.

A further advantage of the dielectric being inactive is a leakage current that is smaller than of aluminium electrolytic capacitor which does not rise considerably even at dead storage. Tantalum electrolytic capacitor thus show a very long life during operation and storage.

The capacitance of the tantalum electrolytic capacitor is very high due to the high dielectric constant and the low thickness of tantalum oxide layer. The use of sintered anodes with a large surface allows very small dimensions that cannot be reached or exceeded by any other capacitor. The tantalum electrolytic capacitor at issue are polarized capacitors. In the case of polarized electrolytic capacitor, the dielectric is structured in such a manner that the flow of current is interrupted in one direction. It is therefore necessary to observe the indications regarding polarity when using these capacitor(positive pole on anode and negative pole on cathode). In the case of tantalum capacitor, a mispolarizing is permissible up to the values indicated in reversal voltage. The tantalum capacitor is a polar electrolytic capacitor. The anode is a porous body of sintered tantalum powder. A layer of tantalum oxide is formed over the whole sintered anode surface by an electrolytic oxidation process.

This oxide layer, which has a high dielectric constant(ϵ =27), functions as the dielectric medium of the capacitor. The final thickness of the layer determines the rated working voltage of the capacitor. Manganese dioxide, a solid semiconducting electrolytic, is deposited in the pores and on the external surface of the formed anode to serve as the cathode. Electrical connection to the cathode is effected by applying a metallic coating to the outer MnO2 layer.

As a result of the high stability of the oxide layer the leakage current to the capacitor is very small, even after prolonged storage. The use of a solid semiconducting electrolytic guarantees high stability of the electrical properties over long periods of time and over a wide range of temperatures and frequencies.



■ FEATURE AND APPLICATION

Feature

The product is a standard type that has been most widely used among tantalum chip capacitors.

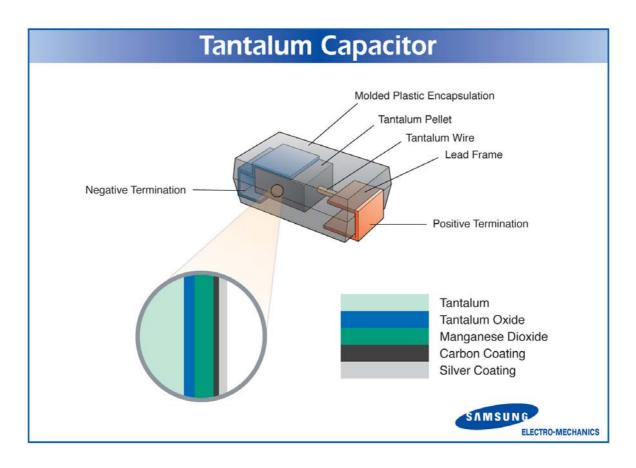
- Molded Case available in four case codes.
- Compatible with automatic pick and place equipment.
- Meets or Exceeds EIA standard 535BAAC .

Application

- General electronic equipment
- Smoothing Circuit of DC-DC Converters & Output side of AC-DC Converters
- De-Coupling Circuit of High Speed ICs & MPUs
- Various Other High Frequency Circuit Applications

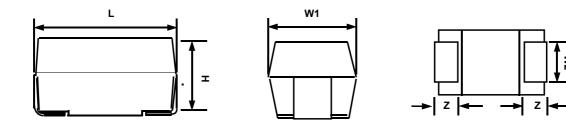


■ STRUCTURE





■ APPEARANCE AND DEMENSION



Code	EIA Codo	DEMENSION (mm)							
Code	EIA Code	L	W ₁	W_2	Н	Z			
Р	2012	2012	2.0 ±0.2	1.25 ±0.2	0.9 ±0.1	1.2 MAX			
Α	3216	3.2 ±0.2	1.6 ±0.2	1.2 ±0.1	1.6 ±0.2	0.8 ±0.3			
В	3528	3.5 ±0.2	2.8 ±0.2	2.2 ±0.1	1.9 ±0.2	0.8 ±0.3			
С	6032	6.0 ±0.3	3.2 ±0.3	2.2 ±0.1	2.5 ±0.3	1.3 ±0.3			
D	7343	7.3 ±0.3	4.3 ±0.3	2.4 ±0.1	2.8 ±0.3	1.3 ±0.3			
Е	7343H	7.3 ±0.3	4.3 ±0.3	2.4 ±0.1	4.1 ±0.3	1.3 ±0.3			

■ PART NUMBERING

lacktriangle Product symbol : (Example) SCN Series, B Case, 6.3V $10^{\mu\text{F}}$ $\pm 20\%$

TC	<u>SCN</u>	<u>0J</u>	<u>106</u>	<u>M</u>	<u>B</u>	<u>A</u>	<u>R</u>
1	2	3	4	⑤	6	7	8

① Tantalum Capacitor

The symbol shows a simplified character of the tantalum capacitor.

2 Type of Series

The symbol shows the type of the capacitor. (SCN, SCS)

SCN: Samsung Capacitor Normal - Standard series

3 Rated Voltage Code

Symbol	0G	0J	1A	1C	1D	1E	1V
DC Rated Voltage	4	6.3	10	16	20	25	35

4 Capacitance Code

Symbol	Capacitance (μF)	Pico Farad (pF)	Symbol	Capacitance (μF)	PicoFarad (pF)
105	1.0	10×10⁵	685	6.8	68×10⁵
106	10.0	10×10 ⁶	476	47	47×10 ⁶
107	100.0	10×10 ⁷	477	470	47×10 ⁷

⑤ Capacitance tolerance Code

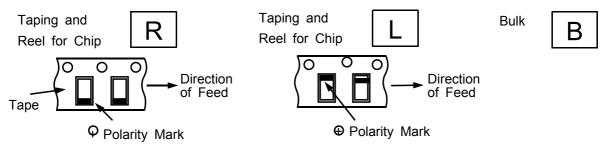
Symbol	Tolerance(%)
K	±10
M	±20

6 Case size Code;

Case	Р	Α	В	С	D	Е
EIA Code	2012	3216	3528	6032	7343	7343H

Packing Code ; (A=7inches, C=13inches)

8 Packing polarity Code

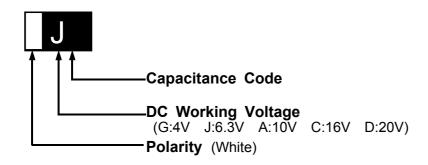




PACKAGING

MARKING

▶ P CASE

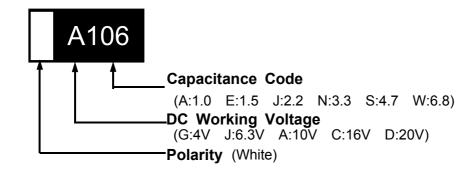


Capacitance Range	1 DIGIT	2 DIGIT
< 1.0 <i>µ</i> F	A Small Letter	A Small Letter
1.0 ^μ F ≤ Cap.< 10 ^μ F	A Capital Letter	A Small Letter
≥ 10 <i>µ</i> F	A Capital Letter	A Capital Letter

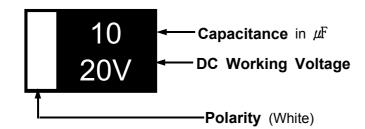
[Code Reference]

μFV	4	6.3	10	16	20
0.22	gj	jj	aj		
0.33					
0.47	gs	js	as	cs	ds
0.68	gw	jw	aw	cw	dw
1.0	Ga	Ja	Aa	Ca	
1.5					
2.2	Gj	Jj	Aj		
3.3	Gn	Jn	An		
4.7	Gs	Js	As		
6.8	Gw	Jw			
10	GA	JA	AA		
15					
22	GJ				

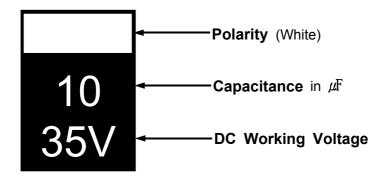
► A CASE



▶ B CASE



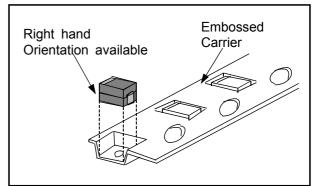
► C,D,E CASE

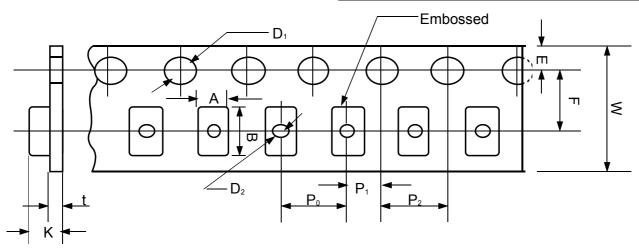


● EMBOSSED PLASTIC TYPE

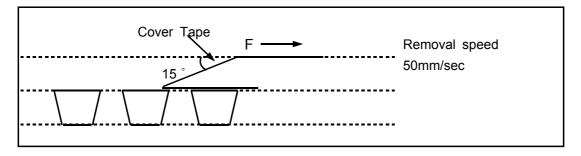
The tantalum chip capacitors shall be packaged in tape and reel form for effective use.

- Tape : Semitransparent embossed plastic
- Cover tape : Attached with press, polyester
- The tension of removing the cover tape, $F{=}10\,{\sim}\,70g$



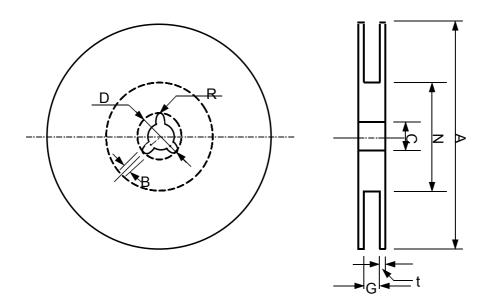


Case Code	W±0.3 (±.012)	F±0.1 (±0.004)	E±0.1 (±.004)	P _o ±0.1 (±0.004)	P ₁ ±0.1 (±0.004)	P ₂ ±0.1 (±0.004)	D ₁ +0.1 (+0.004)	D₂Min.	t	A±0.2 (±0.008)	B±0.2 (±0.008)	K±0.2 (±0.008)
Р									0.2	1.4 (0.055)	2.3 (0.091)	1.4 (0.055)
Α	8 (0.315)	3.5 (0.138)		4 (0.157)				ø 1.0 (0.039)	(0.008)	1.9 (0.075)	3.5 (0.138)	1.9 (0.075)
В			1.75		2	4	ø 1.5			3.3 (0.130)	3.8 (0.150)	2.1 (0.083)
С			(0.069)		(0.079)	(0.157)	(0.059)		0.3	3.7 (0.146)	6.4 (0.252)	3.0 (0.118)
D	12 (0.472)	5.5 (0.217)		8 (0.315)				ø 1.5 (0.059)	(0.012)	4.8	7.7	3.3 (0.130)
E										(0.189)	(0.303)	4.25 (0.167)





• REEL DEMENSION



Tape Width	A±2 (±0.079)	N Min.	C±0.5 (±0.020)	D±0.5 (±0.020)	B±051 (±0.020)		t+0.5 (±0.020)	R
8mm	ø 178	ø 50	ø 13	ø 2 1	2	10 (0.394)	2	0.99
12mm	(7)	(1.969)	(0.512)	(0.827)	(0.079)	14 (0.551)	(0.079)	(0.039)
8mm	ø 330	ø 80	ø 13	ø 21	2	10 (0.394)	2	0.99
12mm	(13)	(3.150)	(0.512)	(0.827)	(0.079)	14 (0.551)	(0.079)	(0.039)

Case Size reference	180mm(7") reel	330mm(13") reel
Р	3,000pcs	
А, В	2,000pcs	8,000pcs
C , D	500pcs	2,500pcs
E	400pcs	2,000pcs

■ CHARACTERISTIC MAP

Capacitance Range

RATED	Size	Capacitance Range (pF)
VOLTAGE	Size	100 1000 10000 100000
	P (2012)	10000
	A (3216)	47000
4V	B (3528)	100000
40	C (6032)	220000
	D (7343)	470000
	E(7343H)	470000
	P (2012)	10000
	A (3216)	22000
6 21//71/	B (3528)	68000
6.3V/7V	C (6032)	150000
	D (7343)	470000
	E(7343H)	470000
	P (2012)	10000
	A (3216)	15000
40)/	B (3528)	47000
10V	C (6032)	100000
	D (7343)	220000
	E(7343H)	220000
	P (2012)	10000
	A (3216)	10000
4014	B (3528)	22000
16V	C (6032)	47000
	D (7343)	100000
	E(7343H)	100000
	P (2012)	10000
	A (3216)	4700
2014	B (3528)	10000
20V	C (6032)	33000
	D (7343)	68000
	E(7343H)	68000
	A (3216)	2200
	B (3528)	6800
25V	C (6032)	22000
	D (7343)	33000
	E(7343H)	33000
	A (3216)	1500
	B (3528)	4700
35V	C (6032)	10000
	D (7343)	22000
	E(7343H)	22000

• Standard value and case size.

▶ SCN Series

	W.V	4V	6.3V	10V	16V	20V	25V	35V
Cap.(μF)		(0G)	(0J)	(1A)	(1C)	(1D)	(1E)	(1V)
0.15	154							Α
0.22	224							Α
0.33	334						Α	Α
0.47	474				Α	Α	Α	В
0.68	684				Α	Α		
1.0	105			Α	Α			В
1.5	155		Α	Α			В	
2.2	225	Α	Α			В		С
3.3	335	Α			В	С	С	С
4.7	475			В	С	С	С	D
6.8	685		В	С	С	С	D	D
10	106	В	С	С	С	D	D	
15	156	С	С	С	D	D		
22	226	С	С	D	D			
33	336	С	D	D				
47	476	D	D					
68	686	D						

► SCS & SCS-P Series

	W.V	4V	6.3V	10V	16V	20V	25V	35V
Cap.(μF)		(0G)	(0J)	(1A)	(1C)	(1D)	(1E)	(1V)
0.15	154							
0.22	224					Р		
0.33	334							
0.47	474					Р		Α
0.68	684						Α	Α
1.0	105	Р	Р	Р	Р	P,A	Α	Α
1.5	155				Α	Α	Α	A,B
2.2	225	Р	Р	P,A	Α	Α	A,B	В
3.3	335		Α	Α	Α	A,B	В	В
4.7	475	P,A	P,A	P,A	A,B	A ,B	В	B,C
6.8	685	Α	Α	A,B	A,B	В	B,C	С
10	106	P,A	P,A,B	P,A,B	A,B	B,C	С	C,D
15	156	A,B	A,B	A,B	B,C	B,C	C,D	C,D,E
22	226	P,A,B	A,B	A,B,C	A,B,C	B,C,D	C,D,E	D,E
33	336	A,B	A,B,C	B,C	C,D	C,D	D,E	D,E
47	476	A,B,C	A,B,C	B,C,D	C,D	D,E	D,E	
68	686	B,C	B,C,D	C,D	C,D	D,E		
100	107	B,C,D	B ,C,D	C,D,E	D,E			
150	157	C,D	C,D	D,E	D,E			
220	227	C,D	C,D,E	D,E	E			
330	330	C ,D,E	C ,D,E	D,E				
470	477	D,E	D,E	E				
680	687	E	D,E					
1000	108	E						

^{*} Red = In Development



▶ SCE Series

	VOLT	4V	6.3V	10V	16V	20V	25V	35V
CAP.		(0G)	(0J)	(1A)	(1C)	(1D)	(1E)	(1V)
1.0	105							A(3000) B(2000 /2500)
1.5	155						A(3000) B(1800 /2000)	B(2500)
2.2	225			A(1800/3000)	A(1800/3500)	A(3000)	B(2500 /3000)	B(2000) C(1000)
3.3	335				A(3500)	A(2500) B(1300 /2000)	B(2000)	C(700 /800)
4.7	475			A(1400)	A(2000) B(800/2000)	A(1800)	B(1500)	B(1500) C(600 /1000)
6.8	685		A(1800)	A(1800)	B(1200)	B(1000) C(700)	C(500/700)	D(500)
10	106		A(1500)	A(900 /1800)	B(800) C(500 /600)	B(1000) C(500/700)	C(300/500)	D(300) E(300)
15	156		A(1500)	A(1000 /1500)	B(800)	C(400 /450)	C(300) D(300)	C(450) D(300) E(300)
22	226		A(900/1200) B(600/800)	B(500/700)	B(600) C(300/375)	C(400) D(300)	D(300)	D(400) E(200/400)
33	336		A(600) B(600)	B(425/650) C(500)	C(225/300)	D(200 /250)	D(300) E(175)	D(300)
47	476	A(500)	B(500) C(300)	B(500/650) C(350) D(100/250)	C(350)	D(100/200) E(150/200)	D(250)	
68	686		B(500) C(150 /300)	C(200 /300) D(100 /200)	C(200 /250) D(150)	D(300)		
100	107		B(400) C(150/300)	C(200 /250) D(100/150)	D(100/150) E(100/150)			
150	157		C (150/250) D(125)	D(100) E(100)	D(125/150) E(100/150)			
220	227	D(100/150)	C(250) D(125) E(150)	D(100/150) E(100)				
330	337	D(100) E(100)	D(100) E(100/150)	D(100/150) E(100)				
470	477	D(100) E(100)	D(100/200) E(100)					
680	687	D(100)						

^{*} Red = In Development



■ RELIABILITY TEST DATA

NO	ITEMS	TEST CONDITION	PERFORMANCE
1	RATED DC VOLTAGE		4~35V
2	CAPACITANCE	MEASURING FREQUENCY: 120±12Hz MEASURING VOLTAGE: 0.5Vrms + 0.5~2V DC MEASURING CIRCUITS: EQUIVALENT SERIES CIRCUIT	CAPACITANCE RANGE $0.1 \sim 330 \mu\text{F}$ TOLERANCE ON CAP. $\pm 10\%$, $\pm 20\%$
3	TANGENT OF LOSS ANGLE	MEASUREMENT SHALL BE MADE UNDER THE SAME CONDITIONS AS THOSE GIVEN FOR THE MEASUREMENT OF CAPACITANCE.	
4	LEAKAGE CURRENT	THE RATED DC VOLTAGE SHALL BE APPLIED TO TERMINALS ACROSS THE TEST CAPACITOR Cx, BY THE METHOD AS SHOWN BELOW. THE LEAKAGE CURRENT SHALL THEN BE MEASURED AFTER CHARGE FOR 5 MIN. MEASURING CIRCUITS WHERE R _s : STANDARD RESISTOR(PROTECTIVE R :1KΩ) V: DC VOLTMETER OR ELECTRONIC VOLTMETER S1: DC POWER SUPPLY SWITCH S2: PROTECTIVE SWITCH FOR A AMMETER Cx: TEST CAPACITOR A): DC AM-METER FOR LEAKAGE CURRENT	0.01CV or 0.5 WHICHEVER IS GREATER
5	IMPEDENCE	AC VOLTAGE(0.5Vrms OR LESS) OF A FREQUENCY SPECIFIED ON NEXT PAGE SHALL BE APPLIED AND THE VOLTAGE DROP ACROSS CAPACITOR TERMINALS SHALL BE MEASURED THE IMPEDANCE SHALL BE CALCULATED BY THE FOLLOWING EQUATION. $Impedance \ Z = \frac{E}{I}$ WHERE $E: \text{VOLTAGE DROP ACROSS THE CAPACITOR TERMINALS}$ $I: \text{CURRENT FLOWING THROUGH THE CAPACITOR}$ (FREQUENCY: 100±10kHz)	



NO	ITEMS	TEST CONDITION PERFORMAN							RMANCE	
		THE C		SHALL BE SU			N TO PF	ROCEDI	JRES SPE	CIFIED
		STEP	STEP TEMP. DURATION		CAPA	NGE IN CITANCE AC)	LOSS	TANGENT OF LOSS ANGLE (D.F.)		KAGE RRENT
		1	25 ±2℃		SPE	ITHIN ECIFIED ERANCE		E 1 ON GE 13	ORI	THIN GINAL IMIT
6	TEMPERATURE STABILITY	2	-55 0 ℃	2 HOURS.		O 0% OF		E 1 ON GE 13	ı	N/A
		3	25 ±2℃	25 MIN.						
		4	+85 ⁺³ ℃	2 HOURS.		+10% OF L VALUE		E 1 ON GE 13	ORI	IIN 10X GINAL IMIT
		5	+125 +3 °C	2 HOURS.		+12% OF L VALUE		E 1 ON GE 13	ORI	IN 12.5X GINAL IMIT
7	SURGE TEST	VOLTA 0.5 MII DISCHA TEMPE AND STAND THERM MEAS + WHERI R1 : P R2 : D Cx : TI V : D S : S' RATE	GE AS SPECIAL MANICH CONTROL C	R1 S R2 SERIES RES RESISTOR(33 TOR	EXT PA 30±5 S DX. 5 M 1,000 C BE STO IDITION MEASU	GE IN A CEC. FOLLOIN 30 SEC YCLES. RED UNDO S TO OBTOREMNIENT + CCX (33Ω)	CYCLE O OWED B C. AT A ER FAIN T.	F 6± Y A	25V	35V
			GE VOLTAGE		8V	13V	20V	26V	32V	45V



	.==		
NO	ITEMS	TEST CONDITION	PERFORMANCE
8	DERATING VOLTAGE	WHEN OPERATING AT HIGH TEMPERATURE RANGE FR OPERATION SHALL BE CARRIED OUT AT A DERATED VIDERATING VOLTAGE VI AT ANY TEMPERATURE BETWEEN SHALL BE CALCULATED BY THE FOLLOWING EQUATION	VOLTAGE OR LESS EEN 85°C AND 125°C N
9	ELECTRODE (TERMINAL STRENGTH)	APPLY PRESSURE IN THE DIRECTION OF THE ARROW AT A RATE OF ABOUT 0.5MM/SEC. UNTIL IT REACHES A BENT WIDTH OF 3MM AND HOLD FOR 30 SEC. THE TEST BOARD SHALL BE IEC 40(S) 541. FOR OTHER PROCEDURES REFER TO IEC 40(S) 541. Pessure rod 10 20 Board 45±2 45±2	THERE SHALL BE NO EVIDENCE OF MECHANICAL DAMAGE. ELECTRICAL CHARACTERISTICS SHALL SATISFY THE INITIAL REQUIREMENT. IF THERE ARE ELECTRODES ON BOTH SURFACES, IT SHALL SATISFY THE ABOVE REQUIREMENT ON WHICHEVER SURFACE IT MAY BE FIXATED ON.

NO	ITEMS	TEST CONDITION	PERFORMANCE
10	ADHESION (ELECTRODE PEELING STRENGTH)	A STATIC LAOD OF 19.6N USING A R0.5 SCRATCH TOLL SHALL BE APPLIED ON THE CORE OF THE COMPONENT AND IN THE DIRECTION OF THE ARROW AND HOLD FOR 5 SEC. THE TEST BOARD SHALL BE IEC 40(S)541. HOWEVER THE BASE MATERIAL SHALL BE G-10 or FR-4 (ANSI GRADE) Scratch tool R0.5 Chip Chip	THERE SHALL BE NO EVIDENCE OF MECHANICAL DAMAGE. ELECTRICAL CHARACTERISTICS SHALL SATISFY THE INITIAL REQUIREMENT. IF THERE ARE ELECTRODES ON BOTH SURFACES, IT SHALL SATISFY THE ABOVE REQUIREMENT ON WHICHEVER SURFACE IT MAY BE FIXATED ON.
11	CORE BODY STRENGTH	A ROD OF 9.8N USING A R0.5 PRESSURE ROD SHALL BE APPLIED TH THE CENTER IN THE DIRECTION OF THE ARROW AND HOLD FOR 10 SEC Pressure R0.5 Chip L > W	THERE SHALL BE NO EVIDENCE OF MECHANICAL DAMAGE. ELECTRICAL CHARACTERISTICS SHALL SATISFY THE INITIAL REQUIREMENT.

NO	ITEMS	TEST CONDITION	PERFORMANCE
12	SOLDERABILITY	SOLDER TEMPERATURE : $230\pm5^{\circ}$ C DIP TIME : 3 ± 0.5 SEC. SOLDER : S63A(KSD 7604) FLUX : ROSIN (KSD 2951)	MORE THAN 75% OF THE TERMINAL SURFACE MUST BE SOLDERED NEWLY.
13	RESISTANCE TO SOLDERING HEAT	PREHEAT: $100\sim110^{\circ}$ FOR 30 SEC. TEMPERATURE: $260\pm5^{\circ}$ C DIP TIME: 10 ± 1 SEC ALL SAMPLES SHALL BE DIPPED IN SOLDER BATH. MEASUREMENT SHALL BE MADE AT ROOM TEMPERATURE AFTER 1~2 HOURS OF COOLING TIME.	CHANGE IN CAPACITANCE: ±5% OF INITIAL VALUE TANGENT OF LOSS ANGLE: LEAKAGE CURRENT: APPEARANCE: THERE SHALL BE NO EVIDENCE OF MECHANICAL DAMAGE.
14	RESISTANCE TO CLEAN TEST	IMMERSION CLEANING THE CAPACITOR SHALL BE CLEANED AT ROOM TEMPERATURE FOR 60sec. USING ISOPROPYL ALCOHOL	THERE SHALL BE NO EVIDENCE OF MECHANICAL DAMAGE. AND MARKING SHALL BE LEGIBLE. ELECTRICAL CHARACTERISTICS SHALL SATISFY THE INITIAL REQUIREMENT.
15	VIBRATION	FREQUENCY: 10 to 55 to 10Hz (in 1 min.) MAX AMPLITUDE: 1.5 mm. DIRECTION OF VIBRATION: IN DIRECTION OF X,Y AND Z AXES TIME: 2 HOURS EACH DIRECTION AND 6 HOURS IN TOTAL DURING THE LAST 30 min. OF VIBRATION IN EACH DIRECTION, THE CAPACITANCE SHALL BE MEASURED 3 TO 5 TIMES. FOR OTHER PROCEDURES REFER TO IEC Pub. 68-2-6. MOUNTING METHOD SOLDER ALUMINA BOARD	CHANGE IN CAPACITANCE: WITHIN: ±5% OF THE INITIAL VALUE TANGENT OF LOSS ANGLE: LEAKAGE CURRENT: APPEARANCE: THERE SHALL BE NO EVIDENCE OF MECHANICAL DAMAGE.
16	MOISTURE RESISTANCE	THE CAPACITOR SHALL BE STORED AT A TEMPERATURE OF 40±2℃ AND RELATIVE HUMIDITY OF 90% TO 95% FOR 500±8 HOURS. ELECTRICAL MEASUREMENTS SHALL BE MADE AFTER BEING BOARD AT ROOM TEMPERATURE FOR 1~2 HOURS. FOR OTHER PROCEDURES REFER TO IEC Pub. 68-2-2.	CHANGE IN CAPACITANCE: WITHIN: ±10% OF THE INITIAL VALUE TANGENT OF LOSS ANGLE: LEAKAGE CURRENT:



N O	ITEMS		TEST CONDITI	PERFORMANCE		
		TEMPERATURE 85℃	VOLTAGE RATED VOLTA	GE	TIME 2,000 HOURS	CHANGE IN CAPACITANCE :
		125°C	DERATED VOLT		2,000 HOURS	INITIAL VALUE TANGENT OF LOSS ANGLE:
17	LOAD LIFE	LEAKAGE CURRENT :				
18	STORAGE AT LOW TEMPERATURE	TEMPERATURE WITHOUT LOAD ELECTRICAL M	EASUREMENTS S STORED AT ROO	ELECTRICAL CHARACTERISTICS SHALL SATISFY THE INITIAL REQUIREMENT.		
		STEP 1	TEMPERATURE		TIME	
		1	-55 ⁰ ℃	3	0 ±3 MIN	CHANGE IN CAPACITANCE :
		2	25 ± 5℃	1	5 ±2 MIN	WITHIN: ±10% OF THE INITIAL VALUE
		3 125 ⁰ °C 30 ±3 MIN		TANGENT OF LOSS ANGLE :		
19	Thermal Shock 4 25 \pm 5°C 15 \pm 2 MIN					LEAKAGE CURRENT :
	THE CAPACITOR SHALL BE SUBJECTED TO EACH SPECIFIED TEMPERATURE FOR EACH SPECIFIED TIME IN THE TABLE AVOBE THESE 4 STEP CONSTITUTES ONE CYCLES SHALL BE PERFORMED CONTINUOUSLY					

■ APPLICATION MANUAL (OPERATIONAL ATTENTION)

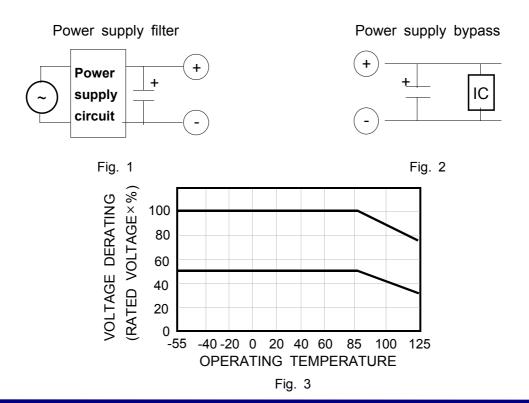
The operational attentions to the use of the tantalum capacitors are as follows:

- Electrical
- Environmental
- Conditions for mounting on equipment and circuit boards
- Mechanical vibration, shock

If the tantalum capacitors are used without satisfying any one of these conditions, the probability of short-circuiting, leakage current, ignition or other problems to occur increases. To avoid such problems, observe the following precautions when using the tantalum capacitors.

Operating Voltage

- ▶ The voltage derating factor should be as great as possible. Under normal conditions, the operating voltage should be reduced to 50% or less of the rating. It is recommended that the operating voltage be 30% or less of the rating, particularly when the tantalum capacitors are used in a low-impedance circuit (see Figs. 1, 2, and 3).
- ► For circuits in which a switching, charging, discharging, or other momentary current flows, it is recommended that the operating voltage be 30% or less of the rating, with a resistor connected in series to limit the current to 300 mA or less.
- ▶ When the tantalum capacitors are to be used at an ambient temperature of higher than 85 °C, the recommended operating range shown in Fig. 3 should not be exceeded.





Ripple

The maximum permissible ripple voltage and current are related to the ratings case size. Please consult us detail informations.

▶ Ripple Current

The maximum permissible ripple current, IMAX, is calculated as follows:

$$I_{MAX} = \sqrt{\frac{P_{MAX}}{ESR(f)}}$$

where:

IMAX: Maximum permissible capacitor ripple current (Arms).

PMAX: Maximum permissible capacitor power loss (W).

Varies with the ambient temperature and case size.

Calculated according to Table 1.

ESR(f): Capacitor equivalent series resistance (Ω).

Since the ESR(f) value varies with the ripple frequency, however, the following correction must be made in accordance with the operating frequency (see Fig. 4).

$$ESR(f) = K \cdot ESR(120)$$

K: Coefficient for the operating frequency (Fig. 4).

ESR(120) = Tan
$$\delta$$
 · Xc = $\frac{\text{Tan } \delta}{2\pi fC}$

where:

ESR(120) : Equivalent series resistance at 120 Hz (Ω).

Xc : Capacitive reactance at 120 Hz (Ω).

C : Electrostatic capacitance at 120 Hz (μ F).

f : Operating frequency (Hz).

Table.1 Maximum permissible power loss values (PMAX) by case size

Ambient	P _{MAX} (W)						
temperature (°C)	Р	Α	В	С	D		
25	0.015	0.030	0.030	0.030	0.050		
55	0.010	0.019	0.019	0.019	0.032		
85	0.005	0.010	0.010	0.010	0.018		

Table.2 Hz VS K

Frequency	K
120	1.0
400	8.0
1k	0.65
10k	0.50
20k	0.45
40k	0.43
100k	0.40
1M	0.35

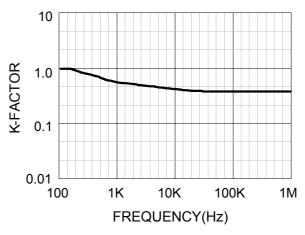
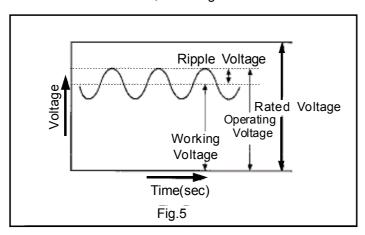


Fig.4 Correction Coefficient(K)

▶ Ripple Voltage

If an excessive ripple voltage is applied to the tantalum capacitors, their internal temperature rises due to Joule heat, resulting in the detriment of their reliability.

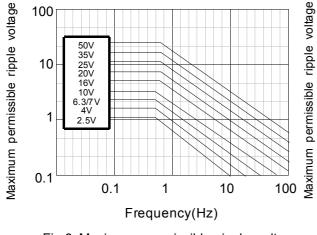


- The tantalum capacitors must be used in such a conditions that the sum of the Working Voltage and ripple voltage peak values does not exceed the rated voltage (Fig. 5)
- Ensure that an reverse voltage due to superimposed voltages is not applied to the capacitors.
- The maximum permissible ripple voltage varies with the rated voltage. Ensure that ripple voltage does not exceed the values shown in Figs 6 and 7. If, however, the capacitors are used at a high temperature, the maximum permissible ripple voltage must be calculated as follows:

 $Vrms(at 55^{\circ}C) = 0.7 x Vrms(at 25^{\circ}C)$

 $Vrms(at 85^{\circ}C) = 0.5 \times Vrms(at 25^{\circ}C)$

 $Vrms(at 125^{\circ}C) = 0.3 \times Vrms(at 25^{\circ}C)$



100 10 | 50V | 35V | 25V | 20V | 16V | 10V | 6.3/7V | 4V | 2.5V | 2.5V

Fig.6 Maximum permissible ripple voltage (P,A,B)

Fig.7 Maximum permissible ripple voltage (C,D,E)

Reverse Voltage

Solid tantalum capacitors are polarized device and may be permanently damaged or destroyed, if connected with the wrong polarity

- ▶ The tantalum capacitors must not be operated and changed in reverse mode. And also the capacitors must not be used in an only AC circuit.
- ▶ The tantalum capacitor dielectric has a rectifying characteristics. Therefore, when a reverse voltage is applied to it, a large current flows even at a low reverse voltage. As a result, it may spontaneously generate heat and lead to shorting.
- Make sure that the polarity and voltage is correct when applying a multi-meter or similar testing instrument to the capacitors because a reverse voltage or overvoltage can be accidentally applied.
- ▶ When using the capacitors in a circuit in which a reverse voltage is applied, consult your local SAMSUNG ELECTRO-MECHANICS agent. If the application of an reverse voltage is unavoidable, it must not exceed the following values:

At 20°C: 10% of the rated voltage of 1 V, whichever smaller.

At 85°C: 5% of the rated voltage or 0.5 V, whichever smaller.

Reliability of Tantalum Capacitors

▶ General

The failure rate of the tantalum capacitor varies with the derating ratio, ambient temperature, circuit resistance, circuit application, etc.

Therefore, when proper selections are made so as to afford additional margins, higher reliability can be derived from the tantalum capacitors. Some examples of actual failure rates are presented below for your reference.

► Failure Rate Calculation Formula

The tantalum capacitors are designed to work at their basic failure rates shown in Table 3 that prevail when the rated voltage is applied for 1000 hours at 85° C.

Table 3 Basic failure rate

TYPE	Classification	Basic failure rate
SCE	Low ESR type	
SCS-P CASE	Miniature type(0805)	1%/1000h
SCS	SCS Smail type	
SCN	Standard type	

$$\lambda$$
use = λ 85 x K_V x K_R

 λuse : Estimated capacitor failure rate under the operating conditions.

 λ 85 : Basic failure rate (Table 3)

 $\ensuremath{K_{\scriptscriptstyle{V}}}$: Failure rate correction coefficient by the ambient temperature and derating factor.

 K_{R} : Failure rate correction coefficient by the circuit resistance, which is the series-connected resistance divided by the voltage applied to the capacitor. This resistance is connected in series when the power supply side is viewed from the capacitor side.

K(derating factor)=operating voltage/rated voltage

Reliability Prediction

Solid tantalum capacitors exhibit no degration failure mode during shelf storage and show a constantly decreasing failure rate(i.e., absence of wearout mechanism) during life tests. this failure rate is dependent upon three important application conditions:DCvoltage, temperature, and circuit impedance.

Estimates of these respective effects are provided by the reliability nomograph. (Figure 9.) The nomograph relates failure rate to voltage and temperature while the table relates failure rate to impedance. These estimates apply to steady-state DC condition, and they assume usage within all other rated conditions.

Standard conditions, which produce a unity failure rate factor, are rated voltage, +85°C, and 0.1 ohm-per-volt impedance.

While voltage and temperature are straight-forward, there is sometimes difficulty in determining impedance. What is required is the circuit impedance seen by the capacitor. If several capacitors are connected in parallel, the impedance seen by each is lowered by the source of energy stored in the other capacitors. Energy is similarly stored in series inductors.

Voltage "de-rating" is a common and useful approach to improved reliability. It can be persued too far, however, when it leads to installation of higher voltage capacitors of much larger size.

It is possible to lose more via higher inherent failure rate than is gained by voltage derating. SAMSUNG typically recommends 50% derating, especially in low impedance circuits.

Failure rate is conventionally expressed in units of percent per thousand hours. As a sample calculation, suppose a particular batch of capacitors has a failure rate of 0.5% / Khr under standard conditions.

What would be the predicted failure rate at 0.7times rated voltage, 60° C and 0.6Ω /V?

The nomgraph gives a factor of 7×10^{-2} and the table gives a factor of 0.4.

The failure rate estimate is then : $0.5 \times 7 \times 10^{-2} \times 0.4$ = 1.4×10^{-2} or 0.014%/Khr

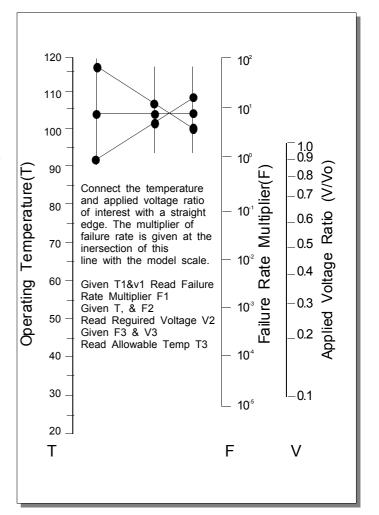


Fig.8 Reliability Nomograph

Table 4 Circuit Impedance Reliability Factors

Circuit Impedance (ohms/volt)	Failure Rate Impedance (multiplying factor)
0.1	1.0
0.2	0.8
0.4	0.6
0.6	0.4
0.8	0.3
1.0	0.2
2.0	0.1
3 or greater	0.07



Mounting Precautions

▶ Limit Pressure on Capacitor Installation with Mounter

A capacitor that has been damaged should be discarded to avoid later problems resulting from mechanical stress.

Pressure must not exceed 4.9 N with a tool end diameter of 1.5mm when applied to the capacitors using an absorber, centering tweezers, or the like. An excessively low absorber setting position would result in not only the application of undue force to the capacitors but capacitor and other component scattering, circuit board wiring breakage, and / or cracking as well, particularly when the capacitors are mounted together with other chips having a height of 1 mm or less.

▶ Flux

- > Select a flux that contains a minimum of chlorine and amine.
- After flux use, the chlorine and amine in the flux remain and must therefore be removed.

▶ Recommended Soldering Pattern Dimensions

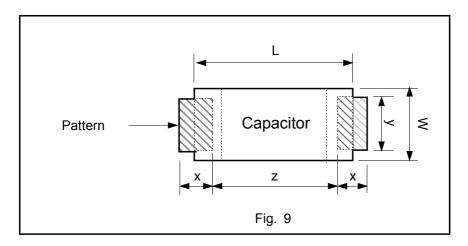


Table 4 Recommended soldering pattern dimensions(mm)

Dimensions	Capacitors size		Pattern dimensions		
Case	L	W	x	у	z
Р	2.0	1.25	1.2	1.1	8.0
Α	3.2	1.6	1.6	1.2	1.2
В	3.5	2.8	1.6	2.2	1.4
С	5.8	3.2	2.3	2.4	2.4
D	7.3	4.3	2.3	2.6	3.8

► Chip Soldering Temperature and Time

Capacitors are capable of withstanding the following soldering temperatures and conditions;

Time: 5 seconds or less

▷ Reflow soldering see figures

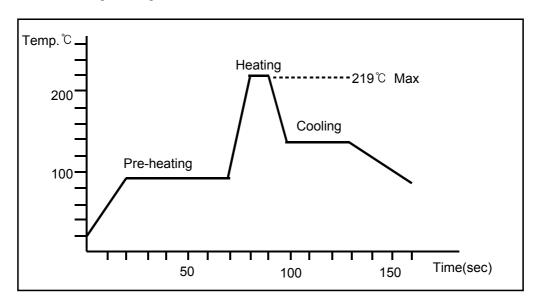


Figure : Typical Temperature Profile of Vapor Phase Reflow Soldering

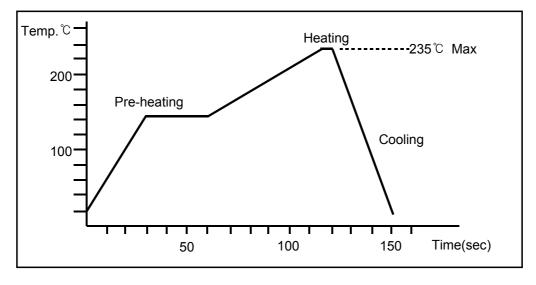


Figure: Typical Temperature Profile of Infrared Reflow Soldering

Soldering with a soldering iron

The use of a soldering iron should be avoided wherever possible. If it is unavoidable, follow the instructions set forth in Table 5. The time of soldering with an iron should be one.

Table 5

Tape	SCN, SCS, SCE, SCS-P CASE
Soldering-iron tip temperature	300°C MAX
Time	3 sec MAX
Soldering-iron power	30 W MAX

► Cleaning after Mounting

The following solvents are usable when cleaning the capacitors after mounting. Never use a highly active solvent.

- Halogen organic solvent (HCFC225, etc.)
- Alcoholic solvent (IPA, ethanol, etc.)
- Petroleum solvent, alkali saponifying agent, water, etc.

Circuit board cleaning must be conducted at a temperature of not higher than 50°C and for an immersion time of not longer than 30 minutes. When an ultrasonic cleaning method is used, cleaning must be conducted at a frequency of 48 kHz or lower, at an vibrator output of 0.02 W/cm3, at a temperature of not higher than 40°C, and for a time of 5 minutes or shorter.

- NOTE 1: Care must be exercised in cleaning process so that the mounted capacitor will not come into contact with any cleaned object or the like or will not get rubbed by a stiff brush or the like. If such precautions are not taken particularly when the ultrasonic cleaning method is employed, terminal breakage may occur.
- NOTE 2: When performing ultrasonic cleaning under conditions other than stated above, conduct adequate advance checkout.

Other

- For further details, refer to EIAJ RCR-2368, Precautions and Guidelines for Using Electronic Device Tantalum Capacitors.
- If you have any questions, feel free to contact your local SAMSUNG ELECTRO-MECHANICS agent.

